

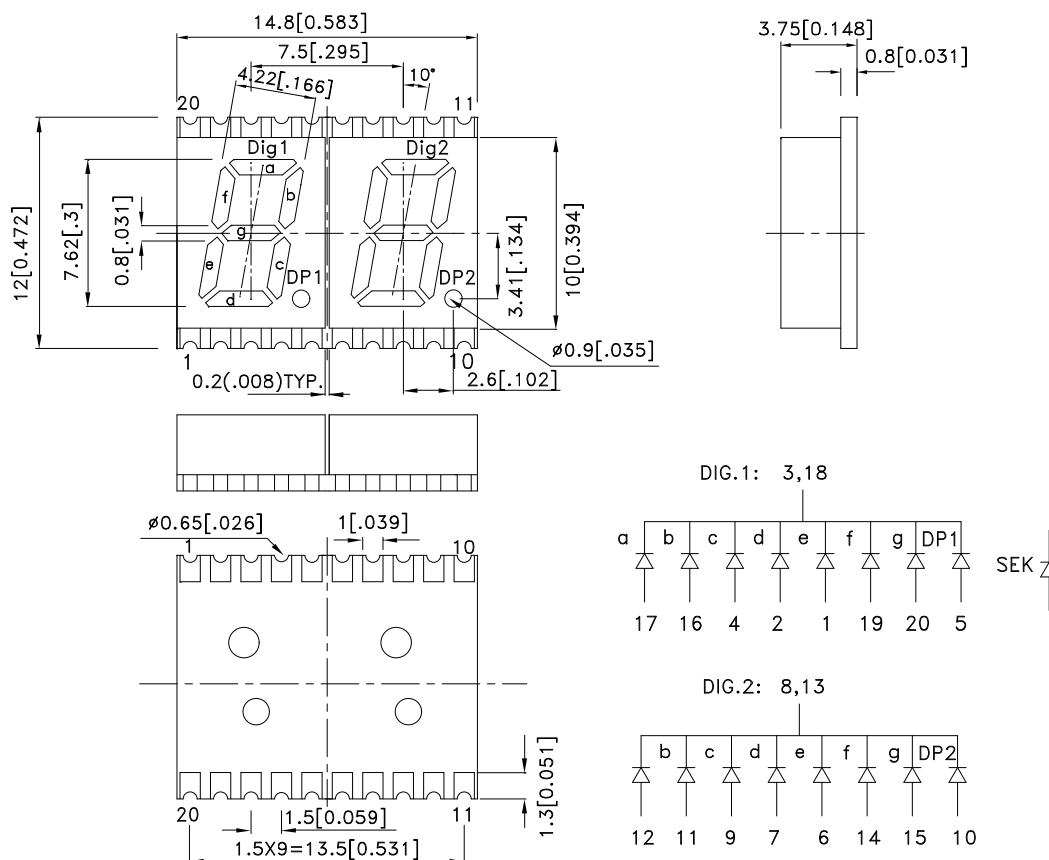
Features

- 0.3 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- PACKAGE :300PCS / REEL.
- GRAY FACE, WHITE SEGMENT.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

Description

The Super Bright Orange device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions& Internal Circuit Diagram



1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
KCDC03-106	Super Bright Orange (InGaAlP)	WHITE DIFFUSED	12000	46000	Common Cathode, Rt. Hand Decimal.

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Orange	610		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Super Bright Orange	601		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Super Bright Orange	29		nm	I _F =20mA
C	Capacitance	Super Bright Orange	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Orange		10	uA	V _R =5V

Notes:

1.Wavelength: +/-1nm.

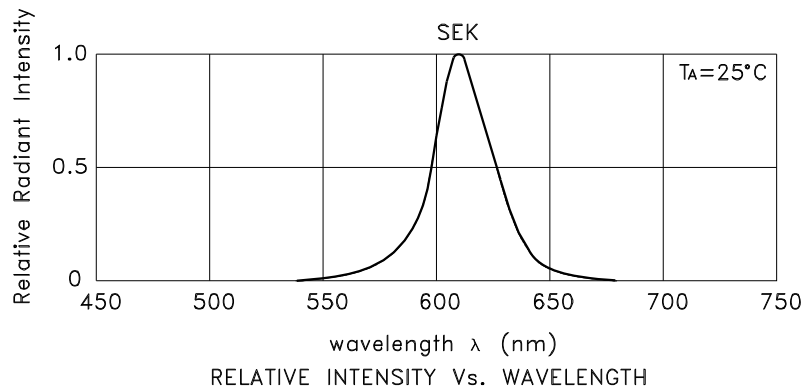
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

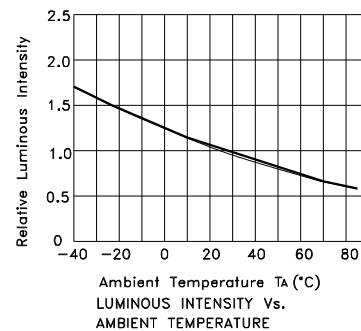
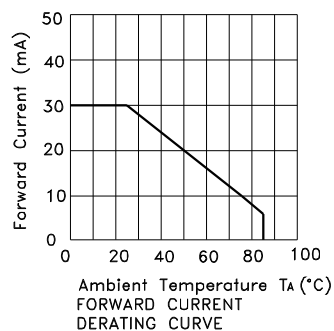
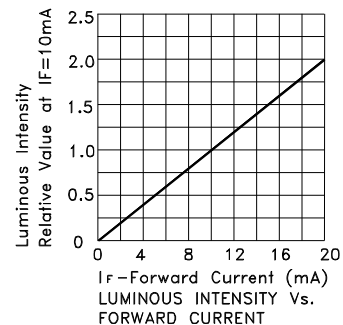
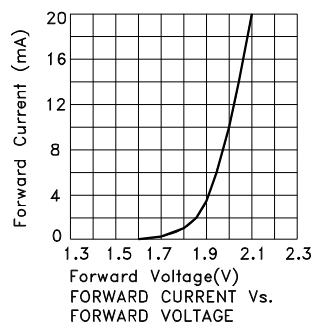
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

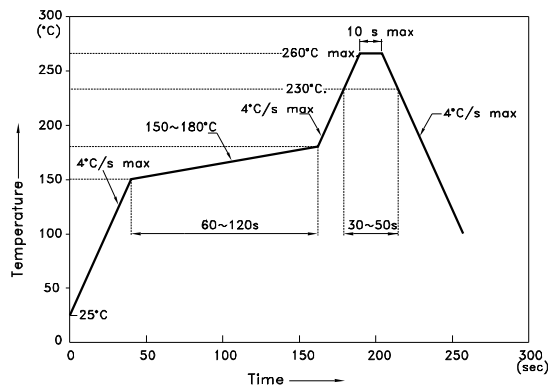


Super Bright Orange KCDC03-106



KCDC03-106

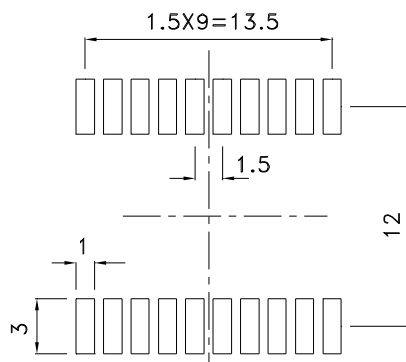
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



Tape Specifications (Units : mm)

